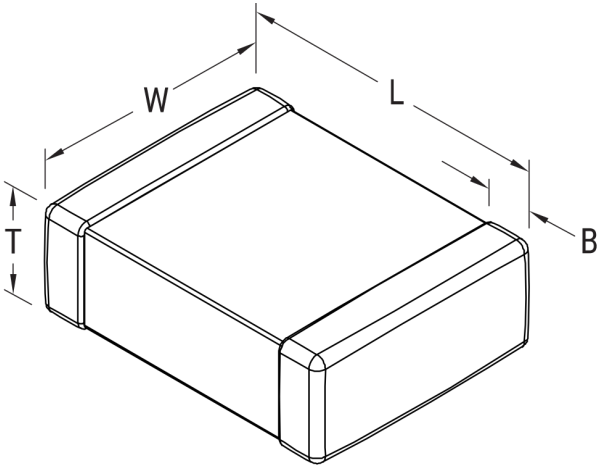


C1808X229BHGACTU

Aliases (C1808X229BHGAC7800)

SMD Comm COG HV Flex, Ceramic, 2.2 pF, +/-0.1 pF, 3000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1808



Click [here](#) for the 3D model.

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	1.6mm +/-0.15mm
B	0.7mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	81 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	2.2 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	+/-0.1pF
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3600 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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